

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJT03P10
Package Type :	SOT-223

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100%	0.04%
Lead Frame	Copper	7440-50-8	97.448%	47.22%
	Iron	7439-89-6	2.300%	
	Phosphorus	7723-14-0	0.100%	
	Zinc	7440-66-6	0.100%	
	Lead	7439-92-1	0.002%	
	Silver	7440-22-4	0.050%	
Soft Solder	Lead	7439-92-1	85.30%	0.20%
	Tin	7440-31-5	4.50%	
	Silver	7440-22-4	2.20%	
	Polyglycol Ether	9038-95-3	5.00%	
	Carboxylic Acid	67762-36-1	0.50%	
	MODIFIED CASTER OIL	61788-85-0	2.50%	
Wire	Copper	7440-50-8	99.995%	0.02%
	Others	N/A	0.005%	
	Copper	7440-50-8	98.00%	0.03%
	Palladium	7440-05-3	1.75%	
	Gold	7440-57-5	0.20%	
	Others	N/A	0.05%	
Mold Compound	Silicon dioxide	60676-86-0	89.00%	50.90%
	Epoxy resin	Trade secret	9.00%	
	Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	1.00%	
	Carbon black	1333-86-4	0.50%	
	3-Trimethoxysilylpropane-1-thiol	4420-74-0	0.50%	
Plating	Tin	7440-31-5	99.9	1.59%
	Other	NA	0.1~1	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.